

SUBSTITUTE ABSTRACT

Abstract

An arrangement for increasing the packing density on a printed circuit with surface mounted electrical components. The printed circuit is formed by two films which are pressed against one another with a dielectric arranged between them. At least one of the mutually opposite faces of the films are fitted with surface mounted electrical components. The via holes are provided in the printed circuit in order to connect the two films, with each via hole being a direct connection between the mutually opposite faces of the films.